

Overview

HP ZBook 17 G5 Mobile Workstation



1. Microphone

2. IR camera

3. HP Privacy Camera

4. HP Privacy Camera shutter

5. Power button

6. Pointstick

7. 3-button touchpad

8. Fingerprint sensor

9. Numeric Keypad

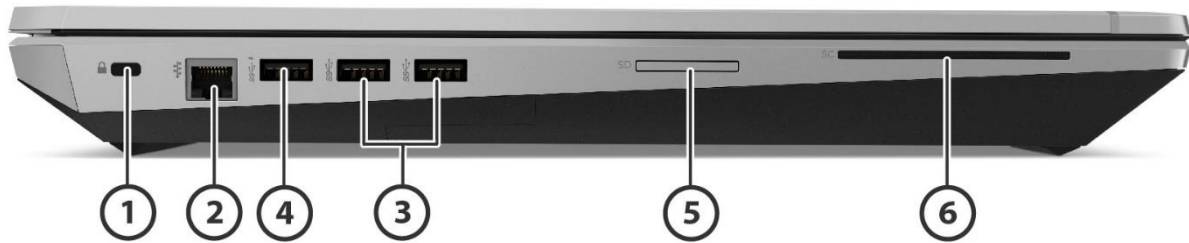
10. Collaboration Keys

11. Speakers

12. Integrated Color Calibration Sensor

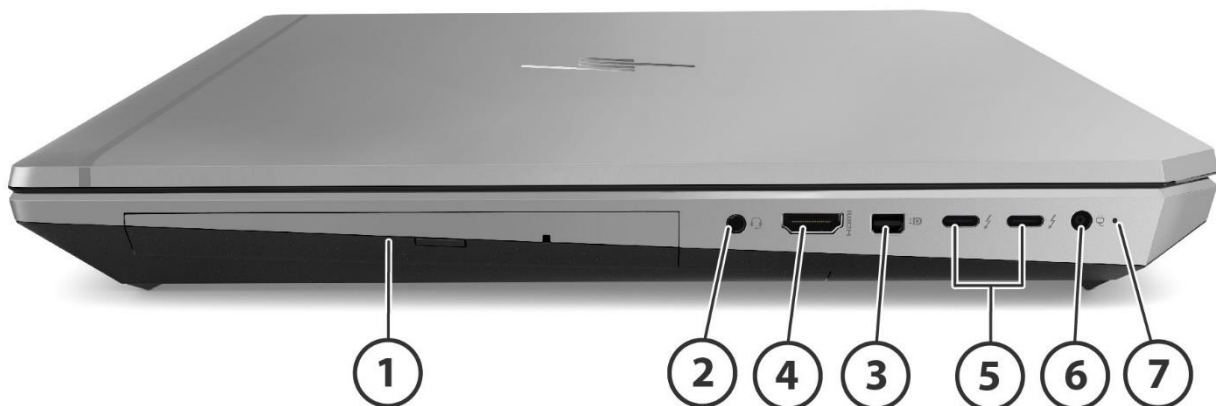
Overview

HP ZBook 17 G5 Mobile Workstation



Left View

- | | |
|------------------------|--------------------------|
| 1. Security cable slot | 4. USB 3.0 charging port |
| 2. RJ-45/Ethernet | 5. SD Card reader |
| 3. 2 USB 3.0 | 6. Smart Card Reader |



Right View

- | | |
|--|-------------------------|
| 1. Optical Disk Drive | 5. Thunderbolt™ 3 ports |
| 2. Stereo microphone in / headphone-out combo jack | 6. Power connector |
| 3. Mini DisplayPort™ | 7. Power LED |
| 4. HDMI 2.0 port | |

Overview



Bottom View

- 1. Fan Venting
- 2. Tool less access
- 3. Keyboard liquid drain

Overview

At A Glance

- Full performance platform with a stylish industrial design, aluminum and magnesium-reinforced chassis in HP's Turbo Silver provides optimal durability and high performance capabilities.
- Featuring HP Collaboration Keyboard with Clickpad to manage most commonly used conferencing functions with a single keystroke. HP Spill Resistant Keyboard with Durakeys to help protect keys from fading.
- ISV certified to provide fast and reliable performance with workstation applications, including manipulation of 3D textures
- HP Performance Advisor for optimal configuration, compatibility and performance
- Tested and passed MIL-STD-810G testing*.
- Workstation-caliber graphic card options:
 - NVIDIA® Quadro® graphics featuring NVIDIA® Optimus technology:
 - NVIDIA® Quadro® P1000 (4GB GDDR5)
 - NVIDIA® Quadro® P2000 (4GB GDDR5)
 - NVIDIA® Quadro® P3200 (6GB GDDR5)
 - NVIDIA® Quadro® P4200 (8GB GDDR5)
 - NVIDIA® Quadro® P5200 (16GB GDDR5)
 - AMD RadeonPro™ featuring AMD Enduro™ technology:
 - WX 4170 (4GB GDDR5)
- Intel® Integrated graphics: Intel® UHD Graphics 630 integrated on Core™ i9 and i7 processors, and Intel® UHD Graphics P630 integrated on Xeon® processors.
- Choice of six-core Intel® Xeon® processors, 8th Generation Intel® Core™ i9 or Core™ i7 processors or quad-core 8th Generation Core™ i5 processors. Intel® Core™ i7 with vPro™, Intel® Core™ i5 with vPro™ technology or Intel® Xeon® with vPro™ technology (optional)
- Populate up to four SODIMM slots supporting up to 64 GB DDR4-2667MHz dual channel memory (up to 128 GB DDR4-2667 MHz). Up to 64GB ECC DDR4-2667MHz dual channel memory available with Intel® Xeon® processors.
- Supports multi-display, including up to four (4) displays without a docking solution, with hybrid graphics enabled. Supports up to six (6) displays or (2) 4K displays with HP Thunderbolt™ Dock G2 (sold separately), with hybrid graphics enabled.
- Choice of 17.3-inch diagonal LED-backlit displays:
 - HD+ IPS eDP anti-glare, 220 nits 85% sRGB (1600x900)
 - FHD IPS eDP anti-glare 300 nits with ambient light sensor 100% sRGB (1920x1080)
 - UHD IPS eDP + PSR Touch-screen with Corning® Gorilla® Glass 4, 400 nits ambient light sensor 100% sRGB (3840x2160)
 - HP DreamColor Technology, UHD IPS eDP + PSR, anti-glare 400 nits, 100% AdobeRGB with 10-bit color (3840x2160) featuring Integrated Color Calibration Sensor on ClickPad to ensure color accuracy
- Two (2) Thunderbolt™ 3 ports (supporting pass through DP 1.4 with discrete, 1.2 with UMA, USB 3.1, PCIe Gen 3 devices) on the new USB-CTM connector, for high speed data/video/audio transfer support.
- Wireless connectivity options:
 - Intel® Dual Band Wireless-AC 9560 802.11 AC/a/b/g/n (2x2) WLAN and Bluetooth® 5.0 combo adaptor (vPro™)
 - Intel® Dual Band Wireless-AC 9560 802.11 AC/a/b/g/n (2x2) WLAN and Bluetooth® 5.0 combo adaptor (non-vPro™)
 - Optional integrated wireless 4G (LTE) mobile broadband module support
- Optimize your audio experience for conference calls and remote collaboration with optional HD webcam, dual-array microphones, premium speakers, HP Noise Cancellation Software, HP Audio Boost, Audio by Bang & Olufsen optimized for high fidelity audio with immersive surround sound with deep, rich bass and crystal-clear dialog without distortion at high volume, and new discrete amp.
- HP Long life battery solution: 6-cell (96 WHr) supporting HP Fast Charge capability
- Four (4) dedicated drive slots, three (3) M.2 slots, and one (1) 2.5" drive bays; Optical disk drive bay with option for extra storage module supporting up to 10TB of data.
- Enterprise grade security features including HP Client Security Manager, HP SureClick, HP WorkWise, and HP SureStart self-healing BIOS, TPM 2.0, HP Touch Fingerprint Sensor, Integrated Smart Card Reader, BIOS Preboot power on, Drive Encryption preboot option, plus optional RAID 1** (mirroring) from HP.

Overview

*MIL STD 810G testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

** RAID 1 Configuration requires 2 NVMe PCIe M.2 drives; both drives must be the same capacity and only available on NVMe technology.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Features

OPERATING SYSTEM

Preinstalled	Windows 10 Pro 64 ¹ Windows 10 Pro for Workstations 64 Windows 10 Home 64 ¹ FreeDOS 2.0
Supported	Windows 10 Enterprise 64 ¹ Red Hat® Enterprise Linux® (REHL) 8 Ubuntu Linux 18.04

¹Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>

PROCESSOR

8th Generation Intel® Core™ i7+ 8750H processor (Core i7 and 16GB Intel® Optane™ memory) with Intel® UHD Graphics 630 (2.2 GHz base frequency, up to 4.1 GHz with Intel® Turbo Boost Technology, 9 MB cache, 6 cores)

8th Generation Intel® Core™ i7-8750H with Intel® UHD Graphics 630 (2.2 GHz base frequency, up to 4.1 GHz with Intel® Turbo Boost Technology, 9 MB cache, 6 cores)

8th Generation Intel® Core™ i5+ 8300H (Core i5 and 16GB Intel® Optane™ memory) with Intel® UHD Graphics 630 (2.3 GHz base frequency, up to 4.0 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)

8th Generation Intel® Core™ i5-8300H with Intel® UHD Graphics 630 (2.3 GHz base frequency, up to 4.0 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)

8th Generation Intel® Core™ i5+ 8400H vPro™ processor (Core i5 and 16GB Intel® Optane™ memory) with Intel® UHD Graphics 630 (2.5 GHz base frequency, up to 4.2 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)

8th Generation Intel® Core™ i5-8400H vPro™ processor with Intel® UHD Graphics 630 (2.5 GHz base frequency, up to 4.2 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)

8th Generation Intel® Core™ i7+ 8850H vPro™ processor (Core i7 and 16GB Intel® Optane™ memory) with Intel® UHD Graphics 630 (2.6 GHz base frequency, up to 4.3 GHz with Intel® Turbo Boost Technology, 9 MB cache, 6 cores)

8th Generation Intel® Core™ i7-8850H vPro™ processor with Intel® UHD Graphics 630 (2.6 GHz base frequency, up to 4.3 GHz with Intel® Turbo Boost Technology, 9 MB cache, 6 cores)

8th Generation Intel® Core™ i9-8950HK processor with Intel® UHD Graphics 630 (2.9 GHz base frequency, up to 4.8 GHz with Intel® Turbo Boost Technology, 12 MB cache, 6 cores)

Intel® Xeon® E-2176M vPro™ processor with Intel® UHD Graphics P630 (2.7 GHz base frequency, up to 4.4 GHz with Intel® Turbo Boost Technology, 12 MB cache, 6 cores)

Intel® Xeon® E-2186M vPro™ processor with Intel® UHD Graphics P630 (2.9 GHz base frequency, up to 4.8 GHz with Intel® Turbo Boost Technology, 12 MB cache, 6 cores)

*Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

**Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system.

***Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.

****Some functionality of Intel® Core™ i5 with vPro™/Core™ i7 with vPro™/Xeon® with vPro™ technology, such as Intel® Active Management technology and Intel® Virtualization technology, requires additional third-party software in order to run.

Availability of future "virtual appliances" applications for Intel® Core™ i5 with vPro™/Core i7 with vPro™/XEON® with vPro™

Features

technology is dependent on third- party software providers. Compatibility with future "virtual appliances" is yet to be determined.

Note: In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD 7th generation and forward processors or provide any Windows®8 or Windows 7 drivers on <http://www.support.hp.com>

Features

CHIPSET

Mobile Intel® CM246

INTEL® CORE™ I5 WITH VPRO™/CORE I7 WITH VPRO™/XEON® WITH VPRO™ TECHNOLOGY CAPABLE

Intel® Core™ i5 with vPro™, Core™ i7 with vPro™ and XEON® with vPro™ technology is a selectable feature that is available on units configured with select processors, a qualified Intel® WLAN module and a preinstalled Windows® operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel® Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state.

* Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

NOTE: Some functionality of Intel® Core™ i5 with vPro™/Core™ i7 with vPro™/Xeon® with vPro™ technology, such as Intel® Active Management technology and Intel® Virtualization technology, requires additional third- party software in order to run. Availability of future "virtual appliances" applications for Intel® Core™ i5 with vPro™/Core i7 with vPro™/XEON® with vPro™ technology is dependent on third- party software providers. Compatibility with future "virtual appliances" is yet to be determined.

Features

GRAPHICS

Intel® Integrated

Intel® UHD graphics 630^{1,2};
Intel® UHD graphics P630^{1,2};

Discrete³

AMD RadeonPro™ WX 4170 with 4 GB dedicated GDDR5 video memory
Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.4 capable

NVIDIA® Quadro® P1000 with 4 GB dedicated GDDR5 video memory
Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.4 capable

NVIDIA® Quadro® P2000 with 4 GB dedicated GDDR5 video memory
Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.4 capable

NVIDIA® Quadro® P3200 with 6 GB dedicated GDDR5 video memory
Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.4 capable

NVIDIA® Quadro® P4200 with 8 GB dedicated GDDR5 video memory
Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.4 capable

NVIDIA® Quadro® P5200 with 16 GB dedicated GDDR5 video memory
Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.4 capable

NOTE 1: UHD content required to view UHD images.

NOTE 2: Intel® HD graphics 630 is configurable as a standalone graphics option; Intel® HD graphics P630 only used when NVIDIA® Optimus™ Technology is enabled.

NOTE 3: NVIDIA® Quadro® mobile professional graphics support up to four independent displays when using a HP ZBook Dock with Thunderbolt™ 3 (sold separately) or DP 1.2 hubs with MST. AMD RadeonPro™ professional graphics support up to six independent displays when using an HP ZBook Dock with Thunderbolt™ 3 (sold separately) or DP 1.2 hubs with MST.

NOTE: Intel® HD Graphics 630 integrated on Core™ i9, Core™ i7 and Core™ i5 processors. Intel® HD Graphics P630 integrated on Xeon® processors.

DisplayPort™ 1.3 protocol features supported on Thunderbolt™ 3 ports:

- Legacy displays (HDMI, DVI, VGA) may be attached to Thunderbolt™ port with the use of a certified dongle.
- DisplayPort™ monitors capable of supporting DisplayPort™ 1.3 may be directly attached to the Thunderbolt™ port to achieve HBR2 with the use a dongle.
- Thunderbolt™ 3 enabled monitors may be directly attached to the Thunderbolt™ port to achieve HBR2 and MST.
- DisplayPort™ 1.3 MST feature ("daisy-chain" feature) is supported through Thunderbolt™ 3 port on Thunderbolt™ 3 enabled devices or DisplayPort™ 1.3 monitors (requires monitor with DisplayPort™ 1.3 MST capability) with the use of a dongle.
- Up to 2 streams (eight lanes) of DisplayPort™ 1.3 are supported over a single Thunderbolt™ 3 port. Up to (2) 4K displays 24/30-bit color depth at 60 Hz or (1) 5K display supported over a single Thunderbolt™ 3 port. (Requires Intel® certified Thunderbolt™ cable).
- DisplayPort™ 1.3 w/MST (Multi-stream Transport): Supports resolutions up to Full 4K, 24/30-bit color depth at 60 Hz, and WUXGA (1920 x1200) monitors, 24/30-bit color depth at 120 Hz.

*Thunderbolt™ 3 is superset port supporting DisplayPort™ 1.3, USB 3.1 Gen 2, and PCIe Gen 3 devices over the new USB-C™ connector. Install all the latest drivers for your Thunderbolt™ device before connecting the device to the Thunderbolt™ port.

Features

Thunderbolt™ cable and Thunderbolt™ device (sold separately) must be compatible with Windows. To determine whether your device is Thunderbolt™ Certified for Windows, see <https://Thunderbolttechnology.net/products>.

Multi-Display Support

Without HP Thunderbolt Dock G2:

HP ZBook 17 with hybrid graphics and without the use of the ZBook dock supports up to a maximum of four independent displays. These four displays are the internal panel plus three external displays connected to either the Mini DisplayPort™ 1.4 or HDMI 2.0 and two of the Thunderbolt™ 3 ports. HP ZBook 17 configuration with Intel® integrated graphics and without the use of the ZBook dock supports up to a maximum of three independent displays. Any three-display combination of the system panel: Mini DisplayPort™ 1.2 or HDMI 2.0, Thunderbolt™ 3, Thunderbolt™ 3.

With HP Thunderbolt Dock G2:

The HP Thunderbolt Dock G2 has Thunderbolt™ 3 port, VGA, two DisplayPort™ 1.3, and a USB-C port. When used together with the HP ZBook 17 configuration with hybrid graphics, a maximum of 6 independent displays are supported. These six displays are internal panel, one external display connected to the system's HDMI port and four external displays connected to the ZBook dock's Thunderbolt™ 3, VGA, and two DisplayPort™ ports. When used together with the HP ZBook 17 configuration with Intel® integrated graphics, a maximum of 3 independent displays are supported. Any three display combination of the system panel, system ports and ZBook Dock ports.

NOTE: When Mini DisplayPort™ 1.4/1.2 and HDMI 2.0 combination is natively used, only HDMI 2.0 connection displays an image.

Features

DISPLAY

Internal

- 17.3-inch diagonal HD+ IPS eDP anti-glare LED-backlit, 220 nits 85% sRGB (1600x900)
- 17.3-inch diagonal FHD IPS eDP anti-glare LED-backlit, 300 nits with ambient light sensor 100% sRGB (1920x1080)
- 17.3-inch diagonal UHD IPS eDP + PSR Touch screen with Corning® Gorilla® Glass 4, LED-backlit, 400 nits, ambient light sensor 100% sRGB (3840x2160)
- HP Dream Color Display, 17.3-inch diagonal UHD IPS eDP + PSR, anti-glare, RG phosphors - LED-backlit, 400 nits, 100% AdobeRGB with 10-bit color (3840x2160) featuring Integrated Color Calibration Sensor on ClickPad to ensure color accuracy.

NOTE: Resolutions are dependent upon monitor capability, and resolution and color depth settings.

STORAGE AND DRIVES

(1) Optical disk drive

Blu-ray R/RE DVD +/-RW SuperMulti DL Drive
2.5" 2 TB SATA SSHD (Hybrid Drive) (8 GB cache) in Optical Bay Carrier

(3) M.2

SATA SED Solid State Drives*

256 GB SATA Self Encrypting Drive (SED) Solid State Drive
512 GB SATA FIPS 140-2 Solid State Drive

NVMe Solid State Drives

16 GB Intel® Optane™ memory**,***
256GB PCIe (NVMe) TLC Solid State Drive
360GB PCIe (NVMe) TLC Solid State Drive
512GB PCIe (NVMe) TLC Solid State Drive
1 TB PCIe (NVMe) TLC Solid State Drive
2 TB PCIe (NVMe) TLC Solid State Drive
256GB PCIe (NVMe) TLC SED Solid State Drive
512GB PCIe (NVMe) TLC SED Solid State Drive

NVMe RAID 1 (optional)

(2) 1 TB PCIe (NVMe) TLC Solid State Drive****
(2) 2 TB PCIe (NVMe) TLC Solid State Drive****

(1) 2.5" Storage Bay Drives*

2 TB 5400 rpm SATA Hard Disk Drive
2 TB SATA SSHD (Hybrid Drive) (8 GB cache)
1 TB SATA SSHD (Hybrid Drive) (8 GB cache)
1 TB 7200 rpm SATA Hard Disk Drive
500 GB 7200 rpm SATA Hard Disk Drive
500 GB 5400 rpm SATA SSHD (Hybrid Drive) (8 GB cache)
500 GB 7200 rpm SATA Self Encrypting Drive (SED) Hard Disk Drive
500 GB 5400 rpm SATA Self Encrypting Drive (SED) FIPS 140-2 Hard Disk Drive
256GB SATA TLC Solid State Drive
1 TB SATA TLC Solid State Drive

HP 3D DriveGuard (Windows only)

The hard drive is mounted directly to the notebook frame, reducing the transmission of shock to the hard drive. Uses three-

Features

axis digital motion detection with intelligent sensitivity to help protect the hard drive during normal use from shock and vibration. The digital accelerometer temporarily halts all data transfer and parks the hard drive when abrupt motion is detected.

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

**Must be configured with either a Hard Disk Drive or a Hybrid Drive. Cannot be configured with an additional M.2 SSD.

***Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system

****RAID 1 Configuration requires 2 NVMe PCIe M.2 drives; both drives must be the same capacity and only available on NVMe technology.

DRIVE CONTROLLERS

(1) 2.5" Storage Bays:

SATA-3 or SATA-2 for HDD

HP Z Turbo Drive:

PCIe NVMe SSD and SATA-3 for SSD

RAID 1

PCIe Gen 3 x4*

RAID:

0, 1 supported**

*RAID 1 Configuration requires 2 NVMe PCIe M.2 drives; both drives must be the same capacity and only available on NVMe technology.

** Raid 0, 1 supported only on SATA drives.

MEMORY

Standard

64 GB DDR4 ECC or 128 GB DDR4, Non-ECC SDRAM (With transfer rates up to 2667MT/s¹)

Four SODIMM slots supporting dual-channel memory; two SODIMMS slots are customer accessible or upgradeable

4GB, 8GB, 16GB, and 32GB SODIMMs (for Intel® Core™ Processors)

8GB and 16 GB ECC SODIMMs (for Intel® XEON® Processors)

Maximum

Non-ECC RAM: Upgradeable to 128 GB with optional 32 GB SODIMMs in all 4 SODIMM slots

ECC RAM: Upgradeable to 64 GB with optional 16 GB SODIMMs in all 4 SODIMM slots

NOTE 1: Intel® allows architectures designed with four DIMM slots to run at 2400 MT/s

NOTE: Maximum memory capacities assume Windows 64-bit operating systems. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.

NETWORKING/COMMUNICATIONS

Communications*

Intel® I219-LM Gigabit* Network Connection (vPro configurations)

Wireless

Support for a broad range of secure, integrated wireless LAN and wireless WAN options featuring support for the latest industry standards. Optional Broadband Wireless (WWAN) requires a Windows® operating system and is available in select countries as a standard, factory configurable feature only. Integrated Bluetooth® is also available (factory configurable only) and can be combined with any of the supported wireless LAN and wireless WAN options.

Features

802.11 Wireless LAN options**

Intel® Dual Band Wireless-AC 9560 802.11ac (2x2) Wi-Fi® and Bluetooth® 5.0 Combo, vPro™
Intel® Dual Band Wireless-AC 9560 802.11ac (2x2) Wi-Fi® and Bluetooth® 5.0 Combo, non-vPro™

Wireless WAN - Mobile Broadband options***

Intel® XMM™ 7360 LTE-Advanced
HP It4132 LTE/HSPA+ 4G Mobile Broadband Module

Near Field Communication¹

NFC Mirage WNC XRAV-1 (NXP NPC300 I2C 10mmx17mm)

*The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

**Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

*** WWAN is an optional feature and requires factory configuration. WWAN use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

¹Sold separately or as an optional feature.

AUDIO/MULTIMEDIA

Audio¹

Audio by Bang & Olufsen, dual stereo speakers
Dual array digital microphone
Optional HP World Facing Microphone
Functions keys for volume up and down
Combo microphone/headphone jack
HD audio; featuring HP Noise Cancellation Software, HP Clear Sound Amp and Skype for Business® Certification

Webcam^{*,**}

Optional HP Privacy Camera (720p HD webcam)

Optional HP Privacy Camera (720p HD webcam) IR camera for face authentication with Windows Hello

- Privacy Camera features sliding camera shutter (non-touch only)
- HD format (widescreen)
- Supports videoconferencing and still image capture
- High quality fixed focus lens
- Video capture at various resolutions up to 1280x720 resolution (720p) and up to 30fps
- M-JPEG compression supports higher frame rates for video capture and videoconferencing
- Improved low light sensitivity
- Improved dynamic range

* HD content required to view HD images.

**Optional or add-on feature.

Features

Note 1: Dual-microphone array when equipped with optional webcam and optional world facing microphone

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

Full-size, spill-resistant backlit HP Premium Collaboration Keyboard to manage most commonly used conferencing functions with a single keystroke with Durakeys to help protect keys from fading, featuring function key control and numeric keypad

Pointing Devices

Clickpad with Image sensor touchpad with on/off button, two-way scroll, gestures, three buttons; Pointstick with three additional pointstick buttons

Buttons and Function Keys

Discrete buttons provide easy access to the following features:

F1 – Display Switching

F2

F3 - Brightness Down

F4 – Brightness Up

F5 – Speaker mute

F6 – Volume down

F7 – Volume up

F8 – Microphone mute

F9 – Keyboard backlight

F10 – NumLock

F11 – Wireless on/off

F12 – Calendar

F13 – Share screen

F14 – Call

F15 – End Call

Features

SOFTWARE AND SECURITY

Preinstalled Software with Windows® Operating System

BIOS

HP BIOSphere Gen4¹
HP Sure Start Gen4 ²
HP DriveLock | HP Automatic DriveLock
BIOS Update via Network
Master Boot Record Security
Power On Authentication
Secure Erase³
Absolute Persistence Module⁴
Pre-boot Authentication
Measured Boot
HP Sure Click
HP LAN-WLAN Protection

Communication / Connectivity

HP Mobile Connect Pro⁵
Native Miracast Support⁶
HP MAC Address Manager (select models only)
HP Host Based Mac Address
HP Wireless Wakeup (select models only)
HP SureConnect

HP Value Add Software

HP 3D DriveGuard ⁶
HP Hotkey Support
HP Recovery Manager
HP Jumpstart
HP Support Assistant¹²
HP Noise Cancellation Software
HP Remote Graphics Software

Microsoft Products

Buy Office
Bing Search
Skype⁸

Manageability

HP Driver Packs ⁹
HP SoftPaq Download Manager (SDM)
HP System Software Manager (SSM) ⁹
HP BIOS Config Utility (BCU) ⁹
HP Client Catalog⁹
HP Manageability Integration Kit for Microsoft SCCM ¹⁰
HP Image Assistant
LANDESK Management ¹¹

For more information on HP Client Management Solutions refer to: <http://www.hp.com/go/clientmanagement>.

Client Security Software

- HP Client Security Suite Gen3¹³
- HP Security Manager (including Credential Manager and Password Manager¹⁵)
- HP Fingerprint Sensor

Features

- IR Camera with Windows Hello
- Power On Authentication
- Device Access Manager
- Windows Defender ¹⁴

HP Value Add Software – Available via HP.com

HP ePrint Driver + JetAdvantage⁷
HP Performance Advisor

For Windows 10, Trusted Platform Module (TPM) 2.0 (Infineon SLB9670). Common Criteria EAL4+ Certified.
For more information on HP Client Security Software Suite, refer to <http://www.hp.com/go/clientsecurity>.

1. HP BIOSphere Gen4 requires Intel® or AMD 8th generation processors.
2. HP Sure Start Gen4 is available on HP Z Workstations products equipped with 8th generation Intel® or AMD processors.
3. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method.
4. BIOS Absolute Persistence module is shipped turned off, and will be activated when customers purchase and activate a subscription. Service may be limited. Check with Absolute for availability outside the U.S. The optional subscription service of Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: <http://www.absolute.com/company/legal/agreements/computrace-agreement>. If Data Delete is utilized, the Recovery Guarantee payment is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either create a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
5. HP Mobile Connect Pro is only available on preconfigured devices with WWAN. For geographic availability refer to <http://www.hp.com/go/mobileconnect>
6. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: <http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast>
7. Requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see <http://www.hp.com/go/eprintcenter>). Requires optional broadband module. Broadband use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Separately purchased data plans or usage fees may apply. Print times and connection speeds may vary.
8. Skype is not offered in China.
9. Not preinstalled, however available for download at <http://www.hp.com/go/clientmanagement>
10. HP Manageability Integration Kit can be downloaded from <http://www8.hp.com/us/en/ads/clientmanagement/overview.html>
11. Subscription required.
12. Requires Windows and Internet Access
13. Requires Windows and Intel® 7th generation processors.
14. Windows Defender Opt In, Windows 10, and internet connection required for updates.
15. HP Password manager requires Windows.

Workstation ISV Certifications

See the latest list of certifications at: <http://www.hp.com/go/isv>

HP Remote Graphics Software

The remote desktop solution for serious workstation users and their most demanding applications.
Download at: <http://www.hp.com/go/RGS>

Features

HP Performance Advisor

HP Performance Advisor enables optimal configuration of HP Mobile Workstations delivering stability and best performance. HP Performance Advisor will guide your system setup allowing a "custom" configuration that best matches the workstation to user requirements.

Download at: <http://www.hp.com/go/performanceadvisor>

Other Standard Security Features

BIOS Update via Network

Pre-boot Authentication

SATA 0,1 port disablement (viaBIOS)

RAID configurations

Serial, USB enable/disable (viaBIOS)

Power-on password (viaBIOS)

Setup password (viaBIOS)

Support for chassis padlocks and cable lock devices

Measured Boot

HP Sure Click¹

Integrated Smart Card Reader

One-Step Logon

Security lock slot

Support for Intel[®] AT

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)

HP Sure Run²

HP Sure Recovery³

TPM

Model: Infineon SLB9670

Version: [7.63.3353.0](#)

Revision: TPM 2.0

FIPS 140-2 Compliant: Yes with Convert TPM to 2.0 (FIPS 140-2) option

Fingerprint Sensor (Optional)

Voltage: 3.0-3.6V

Operating temperature: -20° - 85°C

Imaging current: 31mA

Wake on finger current: 40 uA

Capture rate: 30ms/frame

ESD Resistance: IEC 6100-4-2 4B (+/-15KV)

Detection Matrix: 363 dpi, sensing area 8x8 mm

Smartcard Reader

Model number: Alcor AU9560

FIPS 201 Compliant: Yes

Optional Security Features

HP Fingerprint Sensor (optional)⁴

IR Camera with Windows Hello

Absolute Data Protect* with GPS Tracking - Subscription based security solution providing the ability to track, initiate physical recovery, conduct asset management, and perform remote data delete by utilizing GPS technology. GPS functionality requires HP Mobile Broadband Module.

* The Absolute Data Protect agent is shipped turned off, and must be activated by customers when they purchase a subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S.

Features

1. HP Sure Click is available on most HP PCs and supports Microsoft® Internet Explorer and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.
2. HP Sure Run is available on HP Elite and ZBook products equipped with Intel® or AMD® 8th generation processors
3. HP Sure Recover is available on HP Elite and ZBook PCs with 8th generation Intel® or AMD processors and requires an open, wired network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data
4. Finger Sensor is optional

HP CENTRAL MANAGEMENT

HP offers a variety of scalable hardware, software, and BIOS-based security features to help you defend your organization against viruses and other threats. These integrated security features safeguard what matters to you the most - your data, device and identity. Now, be confident your fleet of devices is protected in multiple layers of HP Client Security protection.

HP BIOS Protection keeps you up and running with enhanced protection against virus attacks and other threats. And if the BIOS is accidentally compromised, the auto recovery feature automatically restores it to its fully functional state.

HP Sure Start detects and negates a BIOS attack with automatic recovery of the BIOS even when the installation is accidentally compromised (i.e. power outage). When HP Sure Start heals the BIOS an event log is generated that an IT administrator can retrieve so the business is aware of a BIOS attack. Golden copy of BIOS is stored in protected nonvolatile memory providing redundant, hardware-based protection against a new generation of attacks. This helps to future-proof your technology and business.

Optional HP Fingerprint Sensor and integrated Smart Card Reader help keep your identity secure. The security cable slot helps keep your notebook physically secure.

You can even permanently destroy data on your hard drive in preparation for your system disposal or redeployment with Secure Erase.

POWER

Power Supply

HP 200W Slim Smart AC adapter
(165 x 79 x 25.4 mm)

Primary Battery

HP Long Life 6-cell Polymer Battery (96 WHr) *

NOTE: Battery is internal and is replaceable by the customer

Battery Life

Battery life up to 17 hours for UMA graphics only configuration **

Battery life up to 16.5 hours for Hybrid graphics configuration **

System Standby Time

Up to 2.3 weeks***

* Available with 3-year limited warranty only

** Windows® 10 MM014 battery life will vary depending on various factors including product model, configuration, loaded

Features

applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See <http://www.bapco.com> for additional details.

*** Standby life will vary depending on various factors including battery, Memory, CPU, EC and LAN chip. The maximum capacity of the battery will naturally decrease with time and usage.

Power Conservation

NVIDIA® Optimus or AMD Enduro™ technology

Hibernation

Standby

ACPI compliance

ENVIRONMENTAL

US ENERGY STAR®

IT ECO declaration

EPEAT® Gold registered*

TCO 5.0 Certification

Low Halogen**

* EPEAT® Gold registered where applicable. EPEAT registration varies by country. See www.epeat.net for registration status by country. See HP's 3rd party option store for solar energy accessory www.hp.com/go/options.

**External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

WEIGHTS, DIMENSIONS AND MATERIAL

Weight

Starting at 7.0 lb. (3.2kg.)

Dimensions (w x d x h)

16.4 in x 11.35 in x 1.3 in

416 mm x 288 mm x 33.5 mm

A deck: Magnesium Aluminum

B deck: Magnesium frame with Aluminum and bond with plastic antenna cover

C deck: Magnesium frame with Aluminum Anodized cover

D deck: magnesium powder coat

Metal Alloy Hinges

NOTE: Height varies depending upon where on the notebook the measurement is made. Weight varies by configuration and components. Weight includes Quad Core CPU, FHD, Intel® UHD graphics, 8GBx1 SODIMM, PCIe NVMe M.2 Drive, wLAN/BT, FPR, 6-cell battery, no wWAN.

PORTS/SLOTS

Ports

Left side:

- 1) RJ-45 (Ethernet)
- (1) USB 3.0 Charging Port
- (2) USB 3.0
- (1) Security lock slot

Right side:

Features

- (1) Power connector;
- (2) Thunderbolt™ 3* (Supporting pass through DisplayPort™ 1.4 with discrete, 1.2 with UMA , USB 3.1 Gen2, PCIe Gen 3 devices)
- (1) Mini DisplayPort™ 1.3
- (1) HDMI 2.0
- (1) Stereo microphone in / headphone-out combo jack;

Thunderbolt™ 3

Thunderbolt™3 ports supports DisplayPort™ 1.4 with discrete, 1.2 with UMA , USB 3.1 Gen 2, and PCIe Gen 3 devices over the new USB-C port connector. The port is compatible with existing DisplayPort™ displays, devices, and cables. Install all the latest drivers for your Thunderbolt™ device before connecting the device to the Thunderbolt™ port. Thunderbolt™ cable and Thunderbolt™ device (sold separately) must be compatible with Windows®. To determine whether your device is Thunderbolt™ Certified for Windows, see <https://thunderbolttechnology.net/products>.

Digital Media Slots

- (1) SD UHS-II Flash Media slot (Supports next generation SD (Secure Digital) and is backward compatible to SDHC, SDXC)
- (1) Integrated Smart Card Reader (Compatible with ISO 7816 compliant Smart Cards PC/SC interface support)

SERVICE AND SUPPORT

Limited 3-year or 1-year limited warranty options available, depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Optional* HP Care Pack Services are extended service contracts which go beyond your standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at <http://www.hp.com/go/cpc>.

*Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.

Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19.5 V	
	Average Operating Power	DreamColor Without DreamColor	25 W Windows® 10 (64-bit) 16.8 W Windows® 10 (64-bit)
	Max Operating Power	< 200 W	
Temperature	Operating	32° to 95° F (0° to 35° C)	
	Non-operating	-4° to 140° F (-20° to 60° C)	
Relative Humidity	Operating	10% to 90%, non-condensing	
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature	
Shock	Operating	40 G, 2 ms, half-sine	
	Non-operating	200 G, 2 ms, half-sine	
Random Vibration	Operating	0.75 grms	
	Non-operating	1.50 grms	
Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048 m)	
	Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)	
Industry Standard Certifications	UL	Yes	
	CSA	Yes	
	FCC Compliance	Yes	
	ENERGY STAR®	Select models*	
	EPEAT	Gold **	
	ICES	Complete	
	Australia / NZ A-Tick Compliance	Complete	
	CCC	Complete	
	Japan VCCI Compliance	Complete	
	KC	Complete	
	BSMI	Complete	
CE Marking Compliance	Complete		
MIL STD 810G	Complete ***		

* Configurations of the HP ZBook 17 that are ENERGY STAR qualified are identified as HP ZBook 17 G5 ENERGY STAR® on HP websites and on <http://www.energystar.gov>.

** EPEAT® Gold registered where applicable. EPEAT registration varies by country. See <http://www.epeat.net> for registration status by country. See HP's 3rd party option store for solar energy accessory www.hp.com/go/options.

*** MIL STD 810G testing is complete and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

For accessibility information on HP products, please visit: <http://www.hp.com/accessibility>.

Technical Specifications – Displays

DISPLAYS

17.3" diagonal HD+ AG LED IPS 85% sRGB (1600 X 900) (220 nits)

Dimensions (W x H)	398.6*251 (mm)	
Weight	550g max	
Diagonal Size	17.3 in (43.9 cm)	
Surface Treatment	Anti-glare	
Contrast Ratio	400:1 (typical)	
Refresh Rate	60 Hz	
Brightness*	220 nits (typical)	
Pixel Resolution	Format	1600 x 900
	Configuration	RGB Stripe
Backlight	LED	
PPI	106	
Viewing Angle	45/45/35/25 (Left/Right/Down/Up) (typical)	

* All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

17.3" diagonal FHD AG LED IPS with Ambient light sensor 100% sRGB (1920 x 1080) (300 nits)

Dimensions (W x H)	398.6*251.0 (mm)	
Weight	550g max	
Diagonal Size	17.3 in (43.9 cm)	
Surface Treatment	Anti-glare	
Contrast Ratio*	800:1 (typical)	
Refresh Rate*	60 Hz	
Brightness*	300 nits (typical)	
Pixel Resolution	Format	1920 X 1080
	Configuration	RGB Stripe
Backlight	LED	
PPI	128	
Viewing Angle	85/85/85/85 (Left/Right/Down/Up) (typical)	

* All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

HP DreamColor Display 17.3" diagonal UHD IPS AG - 10 (8+2) bit color (3840x2160) (400 nits) 100% AdobeRGB

Dimensions (W x H)	398.6*230.95 (mm)	
Weight	550g max	
Diagonal Size	17.3 in (43.9 cm)	
Surface Treatment	Anti-glare	
Contrast Ratio	1000:1 (typical)	
Refresh Rate	60 Hz	
Brightness*	400 nits (typical)	
Color Gamut	100% AdobeRGB	
Pixel Resolution	Format	3840 x 2160
	Configuration	RGB Stripe
Backlight	RG phosphors + B-LED	

Technical Specifications – Displays

Integrate Color Calibration Sensor for HP DreamColor	PPI	254
	Viewing Angle	85/85/85/85 (Left/Right/Down/Up) (typical)
	Chipset	AMS TCS3430
	Sensor type	XYZ tristimulus colorimeter
	System interface	I ² C
	Temperature range:	–30 to 85° C

* All specifications represent the typical specifications provided by HP’s component manufacturers; actual performance may vary either higher or lower.

17.3" diagonal UHD LED IPS, Touch, with Ambient light sensor 100% sRGB (3840x2160) (400 nits)	Dimensions (W x H)	398.6*230.95 (mm)		
	Weight	550 g (max)		
	Surface Treatment	Anti-glare		
	Touch enabled	Yes; Corning Gorilla Glass 4		
	Contrast Ratio	1000:1 (typical)		
	Refresh Rate	60 Hz		
	Brightness*	400 nits (typical)		
	Pixel Resolution	Format	3840 x 2160 (UHD)	
		Configuration	RGB Stripe	
	Backlight	LED		
	PPI	254		
	Viewing Angle	85/85/85/85 (Left/Right/Down/Up) (typical)		

* All specifications represent the typical specifications provided by HP’s component manufacturers; actual performance may vary either higher or lower.

Technical Specifications - Storage and Drives

STORAGE AND DRIVES

Internal Storage

Intel® Optane™ Memory (SSD 16 GB 2280 PCI3-3x2 NVMe 3D Xpoint)	Form Factor	M.2 2280
	Capacity	16 GB
	NAND Type	3D Xpoint
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe Gen3X2
	Maximum Sequential Read	900 MB/s
	Maximum Sequential Write	145 MB/s
	Logical Blocks	28,181,188
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	L1.2

Must be configured with either a standard Hard Disk Drive or Solid-State Hybrid Drive. Cannot be configured with an additional M.2

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

2 TB 5400 rpm SATA Hard Disk Drive	Drive Weight	0.21 lbs (95 g)	
	Capacity	2 TB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Transfer Rate	Synchronous (maximum) 600 MB/s	
	Seek Time (typical reads, including settling)	Single Track	1.5 ms
		Average	13 ms
		Maximum	32 ms
	Cache	128 MB	
	Rotational Speed	5400 rpm	
	Logical Blocks	3,907,029,168	
Operating Temperature	32° to 140° F (0° to 60° C) [case temp]		
Features	ATA Security, S.M.A.R.T., NCQ, Ultra DMA		

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

500 GB 7200 rpm SATA Hard Disk Drive	Drive Weight	0.21 lbs (95 g)
	Capacity	500 GB
	Height	0.28 in (7 mm)
	Width	2.75 in (69.85mm)
	Interface	ATA-8, SATA 3.0

Technical Specifications - Storage and Drives

Transfer Rate	Synchronous (maximum)	600 MB/s (Drive Capability)
Seek Time (typical reads, including settling)	Single Track	1.5 ms ~ 2 ms
	Average	11 ms ~ 13 ms
	Maximum	18 ms ~ 22 ms
Cache	Up To 32 MB	
Rotational Speed	7200 rpm	
Logical Blocks	976,773,168	
Operating Temperature	32° to 140° F (0° to 60° C) [top cover temp]	
Features	ATA Security, S.M.A.R.T., NCQ, Ultra DMA	

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

Technical Specifications - Storage and Drives

1 TB 7200 rpm SATA Hard Disk Drive	Drive Weight	0.21 lbs (95 g)		
	Capacity	1 TB		
	Height	0.28 in (7 mm)		
	Width	2.75 in (69.85mm)		
	Interface	ATA-8, SATA 3.0		
	Transfer Rate	Synchronous (maximum)	600 MB/s	
	Seek Time (typical reads, including settling)	Single Track	1.5 ms	
		Average	13 ms	
		Maximum	32 ms	
	Cache	128 MB		
	Rotational Speed	7200 rpm		
	Logical Blocks	1,953,525,168		
	Operating Temperature	32° to 140° F (0° to 60° C) [top cover temp]		
	Features	ATA Security, S.M.A.R.T., NCQ, Ultra DMA		

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

500 GB Hybrid Drive, 8 GB cache	Drive Weight	0.20 lbs (92 g) ~ 0.21 lbs (95 g)		
	Capacity	500 GB		
	Height	0.28 in (7 mm)		
	Width	2.75 in (69.85 mm)		
	Interface	ATA-8, SATA 3.0		
	Transfer Rate	Synchronous (maximum)	600 MB/s	
	Seek Time (typical reads, including settling)	Single Track	2 ms	
		Average	12 ms	
		Maximum	22 ms	
	Cache	Up to 64MB		
	Rotational Speed	5400 rpm		
	Logical Blocks	976,773,168		
	Operating Temperature	32° to 140° F (0° to 60° C) [case temp]		
	Features	ATA Security, S.M.A.R.T., NCQ, Ultra DMA		

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

1 TB Hybrid Drive, 8 GB cache	Drive Weight	90g		
	Capacity	1 TB		
	Height	0.28 in (7 mm)		
	Width	2.75 in (69.85 mm)		
	Interface	ATA-8, SATA 3.0		
	Transfer Rate	Synchronous (maximum)	600 MB/s	
	Seek Time (typical reads, including settling)	Single Track	1.5 ms	
		Average	13 ms	
		Maximum	32 ms	
	Cache	Up to 128MB		
	Rotational Speed	5400 rpm		
	Logical Blocks	1,953,525,168		

Technical Specifications - Storage and Drives

Operating Temperature 32° to 140° F (0° to 60° C) [case temp]
Features ATA Security, S.M.A.R.T., NCQ, Ultra DMA
 *For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

2 TB Hybrid Drive, 8 GB cache

Drive Weight 90g
Capacity 2 TB
Height 0.28 in (7 mm)
Width 2.75 in (69.85 mm)
Interface ATA-8, SATA 3.0
Transfer Rate **Synchronous (maximum)** 600 MB/s
Seek Time **Single Track** 1.5 ms
(typical reads, including settling) **Average** 13 ms
Maximum 32 ms
Cache Up to 128MB
Rotational Speed 5400 rpm
Logical Blocks 3,907,029,168
Operating Temperature 32° to 140° F (0° to 60° C) [case temp]
Features ATA Security, S.M.A.R.T., NCQ, Ultra DMA

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

500 GB 7200 rpm SATA SED FIPS-140-2 compliant Hard Disk Drive

Drive Weight 0.21 lbs (95g)
Capacity 500 GB
Height 0.28 in (7 mm)
Width 2.75 in (69.85 mm)
Interface ATA-8, SATA 3.0
Transfer Rate **Synchronous (maximum)** 600 MB/s (Drive Capability)
Seek Time **Single Track** 1.5 ms
(typical reads, including settling) **Average** 12 ms
Maximum 21 ms
Cache 32 GB
Rotational Speed 7200 rpm
Logical Blocks 976,773,168
Operating Temperature 32° to 140° F (0° to 60° C) [top cover temp]
Features ATA Security; TCG Opal 2.x, FIPS, S.M.A.R.T., NCQ, Ultra DMA

* FIPS-certified, hardware-based AES-256 encryption image.

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

500 GB 7200 rpm SATA SED Hard Disk Drive

Drive Weight 0.21 lbs (95g)
Capacity 500 GB

Technical Specifications - Storage and Drives

Height	0.28 in (7 mm)	
Width	2.75 in (69.85 mm)	
Interface	ATA-8, SATA 3.0	
Transfer Rate	Synchronous (maximum)	600 MB/s (Drive Capability)
Seek Time (typical reads, including settling)	Single Track	1.5 ms
	Average	12 ms
	Maximum	21 ms
Cache	32 MB	
Rotational Speed	7200 rpm	
Logical Blocks	976,773,168	
Operating Temperature	32° to 140° F (0° to 60° C) [case temp]	
Features	ATA Security, TCG Opal 2.x, S.M.A.R.T., NCQ, Ultra DMA	

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

256 GB SATA TLC Solid State Drive (2.5")

Drive Weight	0.17 lb (78 g)	
Capacity	256 GB	
Height	0.28 in (7 mm)	
Width	2.75 in (69.85 mm)	
Interface	ATA-8, SATA 3.0	
NAND	TLC	
Form Factor (I/O)	2.5 inch	
Performance	Maximum Sequential Read	Maximum Sequential Write
	530 MB/s ~ 560 MB/s	500 MB/s ~ 525 MB/s
Logical Blocks	500,118,192	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security; DIPM; TRIM; DEVSLP	

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

1 TB SATA TLC Solid State Drive (2.5")

Drive Weight	0.17 lb (78 g)	
Capacity	1 TB	
Height	0.28 in (7 mm)	
Width	2.75 in (69.85 mm)	
Interface	ATA-8, SATA 3.0	
NAND	TLC	
Form Factor (I/O)	2.5 inch	
Performance	Maximum Sequential Read	Maximum Sequential Write
	530 MB/s ~ 560 MB/s	500 MB/s ~ 530 MB/s
Logical Blocks	2,000,409,264	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security; DIPM; TRIM; DEVSLP	

Technical Specifications - Storage and Drives

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

256 GB M.2 SED TLC Solid State Drive

Drive Weight	0.02 lb (<10 g)	
Capacity	256 GB	
Height	0.09 in (2.3 mm)	
Width	0.87 in (22 mm)	
Interface	ATA-8, SATA 3.0	
NAND	TLC	
Form Factor (I/O)	M.2 2280	
Performance	Maximum Sequential Read	Maximum Sequential Write
	530 MB/s ~ 560 MB/s	500 MB/s ~ 530 MB/s
Logical Blocks	500,118,192	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security; TCG Opal 2.0, DIPM; TRIM; DEVSLP	

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

512 GB M.2 FIPS-140-2 TLC Solid State Drive

Drive Weight	0.02 lb (<10 g)	
Capacity	512 GB	
Height	0.09 in (2.3 mm)	
Width	0.87 in (22 mm)	
Generation	Micron 1100	
Interface	ACS-3, SATA 3.2	
NAND Type	TLC	
Form-Factor (I/O)	M.2 2280	
Performance	Maximum Sequential Read	Maximum Sequential Write
	Up to 530MB/s	Up to 400MB/s
Logical Blocks	1,000,215,216	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security; TCG Opal 2.0; FIPS; DIPM; TRIM; DEVSLP	

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

360GB M.2 TLC Solid State Drive

Drive Weight	0.02 lb. (10 g)	
Capacity	360 GB	
Height	0.09 in (2.3 mm)	
Width	0.87 in (22 mm)	
Generation	Intel® Pleasant Star	
Interface	PCIe NVMe Gen3X4	
NAND Type	TLC	
Form-Factor (I/O)	M.2 2280	
Performance	Maximum Sequential Read	Maximum Sequential Write

Technical Specifications - Storage and Drives

		Up to 1700MB/s(Compressible Performance)	Up to 600 MB/s(Compressible Performance)
	Logical Blocks	703,282,608	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security (Option); TRIM; L1.2	
		*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.	
256 GB M.2 NVMe TLC Solid State Drive	Drive Weight	0.02 lb (<10 g)	
	Capacity	256 GB	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Generation	Samsung PM961/ Toshiba XG5	
	NAND Type	TLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		2580 MB/s ~ 2600 MB/s	1000 MB/s ~ 1100 MB/s
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security (Option),TRIM; L1.2	
		*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.	
256 GB M.2 NVMe TLC SED Solid State Drive	Drive Weight	0.02 lb (<10 g)	
	Capacity	256 GB	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Generation	Samsung PM961 SED Opal2/ Toshiba XG5 SED Opal2	
	NAND Type	TLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		2580 MB/s ~ 2600 MB/s	Up to 1000 MB/s
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2	
		*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.	
512 GB M.2 NVMe TLC Solid State Drive	Drive Weight	0.02 lb (<10 g)	
	Capacity	512 GB	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Generation	Samsung PM981 / Toshiba XG5	

Technical Specifications - Storage and Drives

NAND Type	TLC	
Form-Factor (I/O)	M.2 2280	
Interface	PCIe NVMe Gen3X4	
Performance	Maximum Sequential Read	Maximum Sequential Write
	2800 MB/s ~ 2900 MB/s	1000 MB/s ~ 1800 MB/s
Logical Blocks	1,000,215,215	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security, TRIM; L1.2	

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

512 GB M.2 NVMe TLC Solid State Drive

Drive Weight	0.02 lb (<10 g)	
Capacity	512 GB	
Height	0.09 in (2.3 mm)	
Width	0.87 in (22 mm)	
Generation	Samsung PM981 SED Opal2/ Toshiba XG5 SED Opal2	
NAND Type	TLC	
Form-Factor (I/O)	M.2 2280	
Interface	PCIe NVMe Gen3X4	
Performance	Maximum Sequential Read	Maximum Sequential Write
	2800 MB/s ~ 2900 MB/s	1000 MB/s ~ 1800 MB/s
Logical Blocks	1,000,215,215	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2	

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

1 TB, M.2 NVMe TLC Solid State Drive

Drive Weight	0.02 lb (<10 g)	
Capacity	1 TB	
Height	0.09 in (2.3 mm)	
Width	0.87 in (22 mm)	
Generation	Samsung PM981 / Toshiba XG5	
NAND Type	TLC	
Form-Factor (I/O)	M.2 2280	
Interface	PCIe NVMe Gen3X4	
Performance	Maximum Sequential Read	Maximum Sequential Write
	2900 MB/s ~ 3000 MB/s	Up to 2000MB/s
Logical Blocks	2,000,409,264	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security, TRIM; L1.2	
Available in RAID 1 config**	Yes	

Technical Specifications - Storage and Drives

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

2 TB, M.2 NVMe TLC Solid State Drive	Drive Weight	0.02 lb (<10 g)	
	Capacity	2 TB	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Generation	Toshiba XG5P	
	NAND Type	TLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 2900MB/s	Up to 2100 MB/s
	Logical Blocks	3,907,029,168	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security, TRIM; L1.2	
	Available in RAID 1 config**	Yes	

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows® 10) disk is reserved for system recovery software.

**RAID 1 Configuration requires 2 NVMe PCIe M.2 drives; both drives must be the same capacity and only available on NVMe technology.

Optical Drives

Blu-ray R/RE DVD+/-RW

SuperMulti DL Drive

Access Times Random: 200 ms CD-ROM (typical)

200 ms DVD-ROM (typical)

250 ms BD-ROM (typical)

Max Data Transfer Rate 24X CD-ROM

8X DVD-ROM

24X CD-R

16X CD-RW

8X DVD+R

8X DVD+RW

6X DVD+R Dual Layer

6X DVD-R Dual Layer

5X DVD-RAM

6X BD-ROM

6X BD-R

2X BD-RE

Transfer Mode UDMA Mode 5

Interface Gen 1 SATA

Supported Media (read) CD-DA, , CD-TEXT, CD-ROM, CD-ROM XA, MIXED MODE CD, CD-I, CD-I Bridge (Photo-CD, Video CD), Multisession CD (Photo-CD, CD-EXTRA, Portfolio, CDR, CD-RW), CD-R, CD-RW, DVD-ROM (DVD-5, DVD-9, DVD-10, DVD-18), DVDR, DVD-RW, DVD+R, DVD+RW. DVD-RAM, BD-ROM, BD-R, BD-RE

Supported Media (write) CD-R, CD-RW, DVD+R, DVD+R DL, DVD+RW, DVD-R, DVD-R DL, DVD-RW,

Technical Specifications - Storage and Drives

DVD-RAM, BD-R, BD-RE

Max Media Capacity

(read)

50.0 GB

Max Media Capacity

(write)

50.0 GB

Transport Tray Loading

Technical Specifications - Security

SECURITY

HP Fingerprint Sensor

Mobile Voltage Operation	3.0V-3.6V Single Supply
Operating Temperature	14° - 167°F (-10° - 75°C)
Current consumption image	36mA
Low latency wait for finger	950 uA
Capture rate	3000 lines/sec
ESD Resistance	IEC 6100-4-2 4B (+/-15KV)
Detection Matrix	200*1 (plus another secondary line); 508 dpi, sensor area 12*3 mm

Smart Card Reader	Smart card standard	PC/SC 2.0 for Windows smart card standard
	Dimensions (L x W x H)	0.41x 0.08 x 0.32 in (10.5 x 2 x 8.2 mm)
	Smart Card support	ISO 7816 Class A and AB smart cards
	Smart Card Interface	Smart Card Interface with T = 0 and T = 1 support Support I2C memory card, SLE4418, SLE4428, SLE4432, SLE4442, SLE4436, SLE5536, SLE6636, AT88SC1608, AT45D041 card and AT45DB041 card via external EEPROM
	Operating systems	Normal Mode With card present, before being suspended: 40.9 mA Without card present, before being suspended: 33.16 mA After being suspended with smart card present: 380 µA After being suspended without smart card present: 380 µA
	Features	<p>Power Saving Mode: With card present, before being suspended: 40.6 mA Without card present: 380 µA After being suspended with smart card present: 380 µA</p> <ul style="list-style-type: none"> • Support single slot • Support T0, T1 protocol • Support I2C memory card, SLE4418, SLE4428, SLE4432, SLE4442, SLE4436, SLE5536, SLE6636, AT88SC1608, AT45D041 card and AT45DB041 card via external EEPROM • Support ISO7816 Class A, B and C (5V/3V/1.8V) card • Implemented as an USB full speed device with bulk transfer endpoint, Mass Storage endpoint • Built-in PLL for USB and Smart Card clocks requirement • Support EEPROM for USB descriptors customization (PID/VID/ iManufacturer/iProduct/Serial Number), Direct Web Page Link, and accessing memory card module. • EEPROM programmable via USB interface • Support software update for memory card module • Support Direct Web Page Link via configuration in external EEPROM • Support short APDU and extended APDU • Compatible with Microsoft USB-CCID driver • Support remote wake up through inserting card/removing card • Support USB selective suspend

Technical Specifications - Security

- Support Power Saving Mode (Using one pin to select between Normal/PWR Saving Mode)
- Support card power over current protection mechanism
- Built in resonator.
- Support USB LPM (Link Power Management) features.
- Embedded clock source.

Technical Specifications – Networking and Communications

NETWORKING/COMMUNICATIONS

Intel® I219-LM Gigabit Network Connection	Ethernet Features	<p>10 Mbit/s operation (10BASE-T; IEEE 802.3; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3. Clauses 40) IEEE 802.3u Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE(Energy Efficient Ethernet) IEEE 802.1as/1588 conformance Jumbo Frame 9K Auto MDI/MDIX Crossover cable detection</p>
	Power Management	ACPI compliant - multiple power modes
	Performance Features	<p>Energy Detect Low Power Mode(Green Ethernet) TCP/IP/UDP Checksum Offload (configurable) Protocol Offload(ARP & NS) Large send offload and Giant send offload Receiving Side Scaling MACSec Offload (802.3ae) Intel® vPro™ iSCSI Boot RSS (Receive Side Scaling) Ultra Low Power</p>
	Manageability	<p>Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status</p>
	Interface	<p>PCI Express 1.1 x1 to fully support ASPM L0s/L1 and CLKREQ. NOTE: Intel® I219-LM Gigabit interface is not PCIe compliant. It operates at half of PCIe specification V1.1 (2.5GT/S) speed.</p>
	NIC Device Driver Name	Intel® Ethernet Network Connection I219-LM

Technical Specifications – Networking and Communications

Intel®XMM™ 7360 LTE-Advanced	Technology/Operating Bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz
	Wireless Protocol Standards	3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone, A-GPS (MS-A, MS-B and XTRA)
	GPS Bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz
	Maximum Data Rates	LTE: 450 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
	Maximum Output Power	LTE: 23 dBm HSPA+: 23.5 dBm
	Maximum Power Consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
	Form Factor	M.2, 3042-S3 Key B
	Weight	5.8g
	Dimensions (Length x Width x Thickness)	1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Technical Specifications – Networking and Communications

HP It4132 LTE/HSPA+ w/GPS	Technology/Operating bands	LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 800 MHz (Band 20, DD800) MHz HSPA+: 2100 (Band 1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz
	Wireless protocol standards	3GPP Release 8 LTE Specification WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification E-GPRS: Class B, Multi-slot class 33, coding schemes CS1 - CS4 and MSC1 - MSC9
	GPS	Standalone, A-GPS
	GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz
	Maximum data rates	LTE: 100 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)
	Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm E-GPRS 1900/1800: 26.5 dBm E-GPRS 900/850: 27.5 dBm GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm
	Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,800 mA (peak); 700 mA (average)
	Form Factor	M.2, 3042-S3 Key B
	Weight	6 g
	Dimensions (Length x Width x Thickness)	1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Technical Specifications – Networking and Communications

Intel® Dual Band Wireless-AC 9560AC 802.11 a/b/g/n/ac (2x2) WiFi + Bluetooth 5.0 Combo Adaptor*	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac
	Interoperability	Wi-Fi certified
	Frequency Band	802.11b/g/n 802.11a/n
		2.402 - 2.482 GHz Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels. 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz Note: No support for this band in Indonesia
	Data Rates	802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15 (20MHz and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
	Modulation	Direct Sequence Spread Spectrum CCK, BPSK, QPSK, 16-QAM, 64-QAM, 256-QAM
	Security¹	<ul style="list-style-type: none"> • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • Cisco Certified Extensions, all versions through CCX4 and CCX Lite • WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between band Access Points
	Output Power²	802.11b : +16dBm minimum 802.11g : +14dBm minimum 802.11a : +14dBm minimum 802.11n HT20(2.4GHz) : +14dBm minimum 802.11n HT40(2.4GHz) : +12dBm minimum 802.11n HT20(5GHz) : +14dBm minimum 802.11n HT40(5GHz) : +12dBm minimum
	Power Consumption	Transmit: 2.0 Watts Receive: 1.6 Watts Idle mode: 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10 mW (WLAN+BT) Radio disabled: 5 mW

Technical Specifications – Networking and Communications

Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity³	802.11b, 1Mbps : -94dBm maximum 802.11b, 11Mbps : -86dBm maximum 802.11g, 6Mbps : -88dBm maximum 802.11g, 54Mbps : -74dBm maximum 802.11a, 6Mbps : -88dBm maximum 802.11a, 54Mbps : -74dBm maximum 802.11n, MCS07 : -69dBm maximum 802.11n, MCS15 : -66dBm maximum 802.11ac, 1SS, MCS-0 : -86dBm maximum 802.11ac, 1SS, MCS-9 : -61dBm maximum 802.11ac, 2SS, MCS-0 : -83dBm maximum 802.11ac, 2SS, MCS-9 : -58dBm maximum	
Antenna Type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm Or Type 1630 : 2.3 x 16.0 x 30.0 mm	
Weight	Type 2230 : 2.8g Or Type 1630 : 2g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating	Temperature
	Non-operating	
Humidity	Operating	Humidity
	Non-operating	
Altitude	Operating	Altitude
	Non-operating	
LED Activity	LED Amber - Radio OFF; LED White - Radio ON	

1. Check latest software/driver release for updates on supported security features.
 2. Maximum output power may vary by country according to local regulations.
 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- * Wireless access point and internet service required. Availability of public wireless access points limited.

HP Integrated Module with Bluetooth 4.2 Wireless Technology

Bluetooth Specification	4.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Technical Specifications – Networking and Communications

Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.												
Receiver Sensitivity	<table border="1"> <thead> <tr> <th>Modulation</th> <th>0.01% BER</th> <th>0.001% BER</th> </tr> </thead> <tbody> <tr> <td>GFSK</td> <td>-80 dBm</td> <td>-70 dBm</td> </tr> <tr> <td>$\pi/4$-DQPSK</td> <td>-80 dBm</td> <td>-70 dBm</td> </tr> <tr> <td>8DPSK</td> <td>-80 dBm</td> <td>-70 dBm</td> </tr> </tbody> </table>	Modulation	0.01% BER	0.001% BER	GFSK	-80 dBm	-70 dBm	$\pi/4$ -DQPSK	-80 dBm	-70 dBm	8DPSK	-80 dBm	-70 dBm
Modulation	0.01% BER	0.001% BER											
GFSK	-80 dBm	-70 dBm											
$\pi/4$ -DQPSK	-80 dBm	-70 dBm											
8DPSK	-80 dBm	-70 dBm											
Power Consumption	<p>Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW</p>												
Range	<p>Legacy Up to 33 ft (10 m) BLE Up to 99 ft (30 m)</p>												
Electrical Interface	USB 2.0 compliant												
Bluetooth Software Supported	Microsoft Windows® Bluetooth Software												
Link Topology	Point to Point, Multipoint Pico Nets up to 7 slaves												
Security	Full support of Bluetooth Security Provisions												
Power Management	<p>Microsoft Windows® ACPI, and USB Bus Support</p> <p>Self-configurable to optimize power conservation in all operating modes, including Standby, Hold, Park, and Sniff</p>												
Certifications	<p>All necessary regulatory approvals for supported countries, including:</p> <p>FCC Class B(47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark</p>												
Bluetooth Profiles Supported	<p>Serial Port Profile (SPP) Service Discovery Application Profile (SDAP) Dial-Up Networking (DUN) Generic Object Exchange Profile (GOEP) Object Push Profile (OPP) Hard Copy Cable Replacement (HCRP) Personal Area Networking Profile (PAN) Human Interface Device Profile (HID) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) Audio Video Remote Control Profile (AVRCP)</p>												

Near Field Communications (NFC) Controller (optional)

Controller Supports	<p>NFC Mirage WNC XRAV-1 (NXP NPC300 I2C 10mmx17mm)</p> <ul style="list-style-type: none"> Windows 8, Proximity Events Windows 7, PC/SC NFC Forum Compliant Near Field Communications Controller
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Dimensions (L x W x H)	Module 25 mm by 10 mm by 2.0 mm
Chipset	NPC100
System interface	I2C
NFC RF standards	standards ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2

Technical Specifications – Networking and Communications

NFC Forum Support Tag Reader	Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2 (PCD-VCD) Mode(1) ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards	
Card Emulation	(PICCVICC)	
Mode	ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa	
Frequency	13.56 MHz	
NFC Modes Supported	Reader/Writer, Peer-to-Peer	
Raw RF Data Rates	106, 212, 424, 848 kbps	
Operating temperature	0°C to 70°C	
Storage temperature	-20°C to 125°C	
Humidity	10-90% operating 5-95% non-operating	
Supply Operating voltage	2.97 to 5.5 Volts	
I/O Voltage	1.8V or 3.3V	
Power Consumption	Booster enable, VCC_BOOST = 5V) Mode Power Consumption,	VBAT= 3.3V, Typical ² Polling 7.3 mA Detected Test Tag Type 1 Total 283.8 mA Net Module 236.8 mA Detected Test Tag Type 2 Total 288.8 mA Net Module 241.8 mA Detected Test Tag Type 3 Total 287.7 mA Net Module 240.7 mA Detected Test Tag Type 4 Total 282.3 mA Net Module 235.3 mA
Antenna connector	0.5mm pitch, 7 connector FPC. Antenna matching is external to module.	
Notes	<ol style="list-style-type: none"> 1. With application or UICC support 2. Actual Power Consumption is dependent on NFC antenna and matching circuit and on the particular polling sequence and period configured. 	

Technical Specifications – Audio and Multimedia

AUDIO/MULTIMEDIA – BANG & OLUFSEN

Hardware	Implementation	Synaptics CX8400 with two NXP TFA9891 discrete smart amplifiers
	Function Key	Volume up, volume down, and mute
	Volume Controls	
	Full Duplex	Yes
	Microphone In	Stereo
	Headphone/Line Out	Stereo
	Integrated Microphone	Yes, (1) dual-array digital microphone and (1) HP World Facing Microphone when equipped with optional webcam
Audio Output Quality	Frequency Response	20 Hz - 20 kHz
	Signal to Noise Ratio	106dB (DAC), 102dB (ADC)
	Total Harmonic Distortion	91dB THD+n on LineOut/HP (0.003%)
	Noise Floor	-110 dB
	Play Sampling Rate(s)	Up to 192kHz
	Record Sampling Rate(s)	Up to 96kHz
	DAC	16, 20 or 24-bit
	ADC	16, 20 or 24-bit
Internal Stereo Speaker	Power Rating	1 Watt/per speaker
	Impedance	8 ohms/per speaker

Technical Specifications – Environmental

POWER

HP 200W Slim Smart AC Adapter	Dimensions	(165 x 79 x 25.4 mm)	
	Weight	530 g	
	Input	Input	100 to 240 VAC
		Input Efficiency	88% min at 115 VAC
		Input frequency range	47 to 63 Hz
	Output	Input AC current	2.9 A at 90 VAC, 1.45 A at 90 VAC
		Output power	200W
		DC output	19.5V
		Hold-up time	5 msec at 115 VAC input
		Output current protection	16A max auto-recovery
	Connector	Over voltage protection	29V max automatic shutdown
		3 pin/grounded, 4.5mm barrel type	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16404 ft (0 to 5,000 m)
Storage Humidity		10% to 95%	
EMI and Safety Certifications	CE Mark- full compliance with LVD and EMC directives; Worldwide safety standards- IEC950, EN60950, UL1950, Class 1, SELV; Agency approvals- C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCIB, NOM-1 NYCE; MTBF- over 200,000 hours at 25°C ambient condition.		

HP Long Life 6-cell Polymer Battery (96 WHr)	Dimensions (H x W x L)	9.9x3.26x0.726 in (25.16x8.29x1.844cm)		
	Weight (max)	1.12lb (420g)		
	Cells/Type	6-cell; Polymer		
	Energy	Voltage	11.4V	
		Amp-hour capacity	8.42Ah	
		Watt-hour capacity	96Wh	
	Temperature	Operating (Charging)	32° to 113° F (0° to 45° C)	
		Operating (Discharging)	14° to 140° F (-10° to 60° C)	
		Non-operating	-4° to 140° F (-20° to 60° C)	
	Battery Re-Charge Time	System in OFF or Standby Mode	3 hours	
		System ON	3 to 5 hours	
	Fuel Gauge LED	No		
	Warranty*	3 year		
	Charge Rate	0.7C; HP Fast Charge 90% charge in 90 minutes		
	Compatible with optional Travel Battery	N/A		

* 3-year platform warranty is required for a 3-year Long Life Battery warranty.

Technical Specifications – Environmental

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT® Gold registered in the United States. See <http://www.epeat.net> for registration status in your country.
- TCO NB 5.0

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a “Typically Configured Notebook”.

Energy Consumption (in accordance with US ENERGY STAR® test method)

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Sort idle)	21.34 W	21.54 W	21.31 W
Normal Operation (Long idle)	9.94 W	10.51 W	10.55 W
Sleep	1.29 W	1.42 W	1.32 W
Off	0.47 W	0.53 W	0.47 W

Note:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	73 BTU/hr	74 BTU/hr	73 BTU/hr
Normal Operation (Long idle)	34 BTU/hr	36 BTU/hr	36 BTU/hr
Sleep	4 BTU/hr	5 BTU/hr	5 BTU/hr
Off	2 BTU/hr	2 BTU/hr	2 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

	Sound Power (L _{WA} d, bels)	Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle	2.8	16
Fixed Disk – Random writes	3.2	24
Optical Drive – Sequential reads		

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

- 4 USB ports
- 2 Thunderbolt™ 3 ports
- 2 2.5” Storage Bay Drives
- 2 M.2 SATA SED Solid State Drives

Technical Specifications – Environmental

- 1 Smart Card Reader
- 1 SD Card reader
- 4 SODIMM memory slots
- 1 HDMI 2.0 port

Spare parts are available throughout the warranty period and or for up to “5” years after the end of production.

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:
Mercury greater than 1ppm by weight
Cadmium greater than 20ppm by weight

Battery size: CR2032 (coin cell)
Battery type: Polymer
Battery size: 6-cell high capacity Polymer battery

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 0.0% post-consumer recycled plastic (by wt.)

This product is 95.2% recycle-able when properly disposed of at end of life.

Packaging Materials

External:	PAPER/Corrugated	373 g
Internal:	PLASTIC/Polyethylene Expanded - EPE	64 g
	PLASTIC/Polyethylene low density – LDPE	33 g
	PAPER/Paper	92 g

The plastic packaging material contains at least 81.5% recycled content.

The corrugated paper packaging materials contains at least 80.0% recycled content.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf>):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.

Technical Specifications – Environmental

- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) – except for wires and cables, has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <http://www.hp.com/go/reuse-recycle> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: <http://www.hp.com/go/recyclers>. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

<http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html>

Eco-label certifications

<http://www8.hp.com/us/en/hp-information/environment/ecolabels.html>

ISO 14001 certificates:

<http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842>

and

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf>

COUNTRY OF ORIGIN

China

Options and Accessories (sold separately and availability may vary by country)

Type	Description	Part #
Display	HP Z24n G2 24-inch Display	1JS09A4#xxx
	HP Z27n G2 27-inch Display	1JS10A4#xxx
	HP DreamColor Z27x G2 27-inch Studio Display	2NJ08A4#xxx
	HP DreamColor Z31x 31-inch Studio Display	Z4Y82A4#xxx
	HP Z32 31.5-inch UHD Display	1AA81A4#xxx
	HP Z38c 37.5-inch Curved Display	Z4W65A4#xxx
Memory	HP 4GB DDR4-2666 SODIMM	4VN05AA#ABA
	HP 8GB DDR4-2666 SODIMM	4VN06UT#ABA
	HP 16GB DDR4-2666 SODIMM	4VN07AA/UT#ABA
	HP 8GB DDR4-2666 ECC SODIMM	4UY11AA
	HP 16GB DDR4-2666 ECC SODIMM	4UY12AA
Cases	HP 17" Business Top Load Case	2UW02AA
	HP 17" Business Backpack	2SC67AA
Docking	HP USB-C™ Universal Dock	1MK33AA
	HP USB-C™ Mini Dock	1PM64AA
	HP Thunderbolt™ Dock 230W G2	2UK38AA
	HP Thunderbolt™ Dock Audio	3AQ21AA
	HP USB-C™ Dock G4	3FF69AA#xxx
	HP TB Dock G2 w/Combo Cable	3TR87AA#xxx
	HP Travel Hub	TOK30AA
	HP 3005pr USB 3.0 Port Replicator w/ USB-C™ Adapter	Y4H06AA
Input/Output - Mice	HP Wireless Premium Mouse	1JR31AA
	HP USB Premium Mouse	1JR32AA
	HP Slim Bluetooth Mouse	F3J92AA#xxx
	HP USB Travel Mouse	G1K28AA#xxx
	HP Comfort Grip Mouse	H2L63AA
	HP X4000 Bluetooth Mouse	H3T50AA#xxx
	HP 3-Button Laser Mouse	H4B81AA#xxx
	HP Ultra Mobile Wireless Mouse	H6F25AA#xxx
	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Slim USB Keyboard and Mouse	T6T83AA
HP Wireless (Link-5) Keyboard	T6U20AA	
Power Adapters	HP 200W SLIM Smart AC Adapter	4SC19AA/UT#xxx
Battery	ZBook G5 Replacement Battery 96Whr Battery	4ME80AA
Adapters	HP HDMI to DVI adapter	F5A28AA
	HDMI to VGA Adapter	H4F02AA

Options and Accessories (sold separately and availability may vary by country)

	USB 3.0 to RJ45	N7P47AA
	HP USB-C™ to VGA Adapter	N9K76AA
	USB-C™ to RJ45	V7W66AA
	HP USB-C™ to USB Hub	Z6A00AA
Storage - External Storage	HP 256GB M2 NVME PCIe SSD (2280)	V3K66AA
	HP 512GB M2 NVME PCIe SSD (2280)	V3K67AA
	HP 256GB TLC PCI-e 3x4 NVMe M.2 SSD	1FU87AA
	HP 512GB TLC PCI-e 3x4 NVMe M.2 SSD	1FU88AA
	HP USB External DVDRW Drive	F2B56AA
Security	HP Nano Keyed Cable Lock	1AJ39AA
	HP Nano Dual Head Keyed Cable Lock	1AJ41AA
	HP Docking Station Cable Lock	AU656AA#XXX
	HP Keyed Cable Lock	TOY14AA
	HP Combination Lock	TOY15AA
	HP Essential Combination Lock	TOY16AA
	HP Keyed Cable Lock 10mm	T1A62AA
	HP Dual Head Cable Lock (Non-Master key)	T1A64AA
	HP Dual Head Cable Lock (Master Key)	T1A65AA
	HP 3 year Next business day onsite Hardware Support w/Accidental Damage Protection-G2 for Notebooks	UF631E
Collaboration	HP Elite Presenter Mouse	2CE30AA#xxx
	HP UC Conferencing Keyboard	K8P74AA#xxx
	HP Stereo 3.5mm Headset	T1A66AA
	HP Stereo USB Headset	T1A67AA
	HP USB Collaboration Keyboard	Z9N38AA
	HP Wireless Collaboration Keyboard	Z9N39AA#xxx
	HP Wireless Premium Keyboard	Z9N41AA#xxx

Summary of Changes

Date of change:	Version History:		Description of change:
May 30, 2018	From v1 to v2	Changed	Environmental Data
June 7, 2018	From v2 to v3	Changed	Format Changes
June 26, 2018	From v3 to v4	Changed	Front view, Processors, Storage and Drives, Software and Security, Power, System Unit, Security sections and format changes
August 27, 2018	From v4 to v5	Changed	Format
October 15, 2018	From v5 to v6	Added	Added features to support October refresh
January 18, 2019	From v6 to v7	Changed	Multi-Display Support, SOFTWARE AND SECURITY, Longevity and Upgrading sections
February 20, 2019	From v7 to v8	Changed	SureView Removed
June 18, 2019	From v8 to v9	Changed	Display and Storage sections
July 23, 2019	From v9 to v10	Changed	At a glance and Port sections
July 30, 2019	From v10 to v11	Changed	Multimedia removed from Software and security section
November 13, 2019	From v11 to v12	Changed	OPERATING SYSTEM and WEIGHTS, DIMENSIONS AND MATERIAL sections

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